

## Product Change Notification

(Notification – P2206027-DI)

(PC-SOC-A002A/E)

June 2, 2022

**To:** *Our Valued Distribution Customer*

The purpose of this notification is to communicate a product change of select Renesas Electronics America, Inc. (REA) devices.

This notification announces the following changes to select RX/T1 devices in the 320pin BGA package. See the appendix for additional details.

- Addition of Advanced Semiconductor Engineering, Inc. as an Assembly Site
- Addition of King Yuan Electronics Co., Ltd. as a Final Test (Sorting) Site
- Additional Package Outline
- Additional Marking Font

The new additional device has a new additional part number, and there is a change to the form. There is no impact to the specifications, fit, characteristics, quality & reliability of the products.

**Affected Products:** A review of our records indicates the list of products in the appendix may affect your company.

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

**Key Dates:**

Shipments from REA of the new additional part numbers begins.
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March 1, 2023
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**Response:** No response is required. REA will consider this notification approved 30 days after its issue. If you anticipate volumes beyond your regular rate prior to the transition date, please contact your REA sales representative with a forecast of your requirements.

If the customer provides a timely acknowledgement, the customer shall have 90 days (an additional 60 days) from the date of receipt of this notification in which to make any objections to the notification. If the customer does not make any objections to this notification within 90 days of the receipt of the notification, then Renesas will consider the notification as approved. If customer cannot accept the notification, then the customer must provide Renesas with a last time buy demand and purchase order.

Please contact your REA sales representative for any questions or comments. Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.

**Appendix A: Affected Part Numbers**

Booking PN	New Additional PN
R7S910002CBG#AC0	R7S910002CBA#BC0
R7S910018CBG#AC0	R7S910018CBA#BC0
R7S910006CBG#AC0	R7S910006CBA#BC0
R7S910025CBG#AC0	R7S910025CBA#BC0
R7S910007CBG#AC0	R7S910007CBA#BC0
R7S910026CBG#AC0	R7S910026CBA#BC0
R7S910011CBG#AC0	R7S910011CBA#BC0
R7S910027CBG#AC0	R7S910027CBA#BC0
R7S910013CBG#AC0	R7S910013CBA#BC0
R7S910028CBG#AC0	R7S910028CBA#BC0
R7S910015CBG#AC0	R7S910015CBA#BC0
R7S910035CBG#AC0	R7S910035CBA#BC0
R7S910016CBG#AC0	R7S910016CBA#BC0
R7S910036CBG#AC0	R7S910036CBA#BC0
R7S910017CBG#AC0	R7S910017CBA#BC0

**Appendix B: Change Summary**

Item	Current	New Additional
Assembly (Location)	Amkor Technology Japan, Inc. (Hakodate, Japan)	Advanced Semiconductor Engineering, Inc. (Kaohsiung, Taiwan)
Final Test (Location)	Amkor Technology Japan, Inc. (Kumamoto, Japan)	King Yuan Electronics Co., Ltd. (Chu-Nan, Taiwan)
Package	No Change	Changed
Tester	No Change	
Test Program	No Change	
Marking	No Change	Changed

### Appendix C: Package Outline Change

Current product					Additional product				
	Symbol	Dimension in Millimeters				Symbol	Dimension in Millimeters		
		Min.	Nom.	Max.			Min.	Nom.	Max.
Package size	D	16.80	17.00	17.20	Package size	D	16.80	17.00	17.20
Package size	E	16.80	17.00	17.20	Package size	E	16.80	17.00	17.20
Total thickness	A	-	-	2.30	Total thickness	A	-	-	<b>1.75</b>
Stand off	A1	0.35	0.40	0.45	Stand off	A1	0.35	0.40	0.45
Ball pitch	e	-	0.80	-	Ball pitch	e	-	0.80	-
Ball width	b	0.45	0.50	0.55	Ball width	b	0.45	0.50	0.55
Ball offset (Package)	x1	-	-	0.20	Ball offset (Package)	x1	-	-	0.20
Ball offset (Ball)	x2	-	-	0.08	Ball offset (Ball)	x2	-	-	0.08
Coplanarity	y	-	-	0.10	Coplanarity	y	-	-	<b>0.12</b>
Mold parallelism	y1	-	-	0.20	Mold parallelism	y1	-	-	0.20

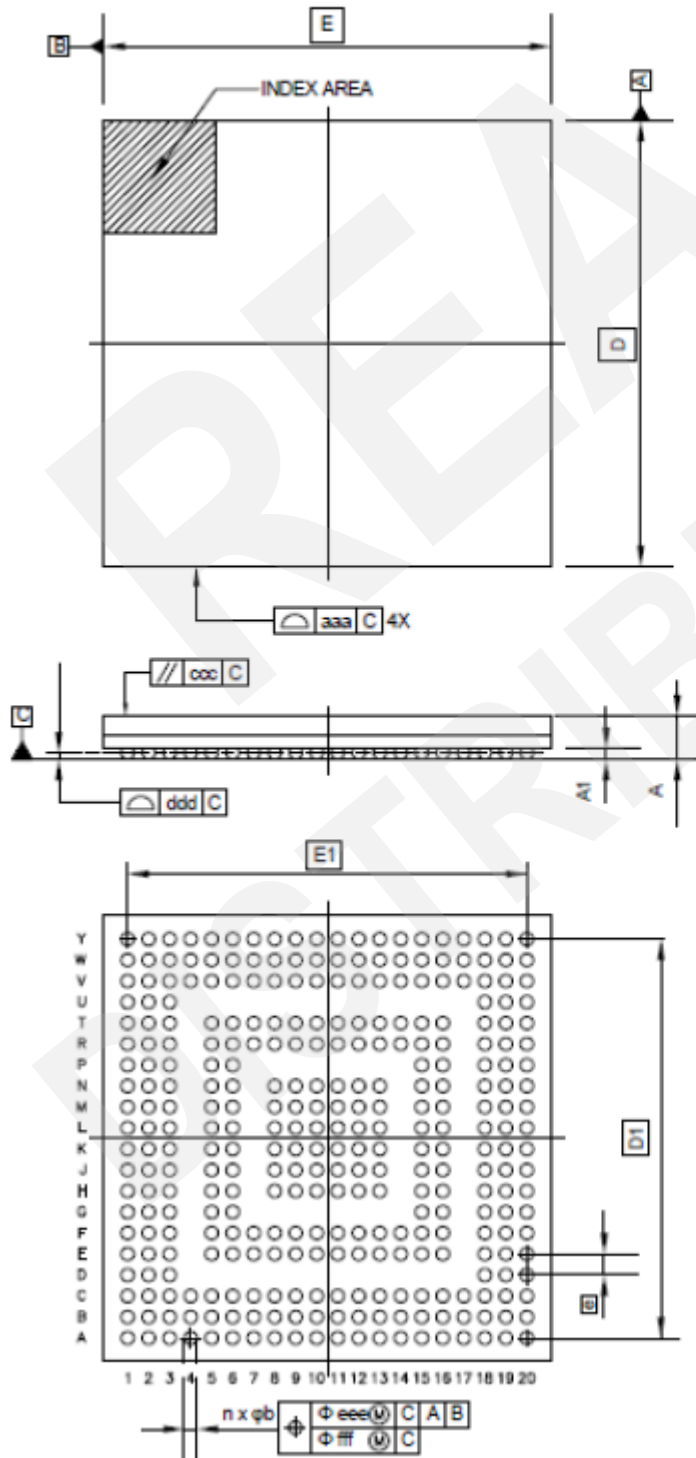
### Appendix D: Marking Change

Current product		Additional product	
<p>           型名 Type Code → R7S9100XX            トレースコード Trace Code → RZ/T1            EIAコード EIA Code → *****            生産国コード Mark. Country Origin → JAPAN         </p>	<p>           Type Code → XXXXXXXXXXXX            Trace Code &amp; EIA Code → RZ/T1 XXXX            生産国コード Mark. Country Origin → TAIWAN         </p>	<p>Engineering Build (N/A for MP)</p>	



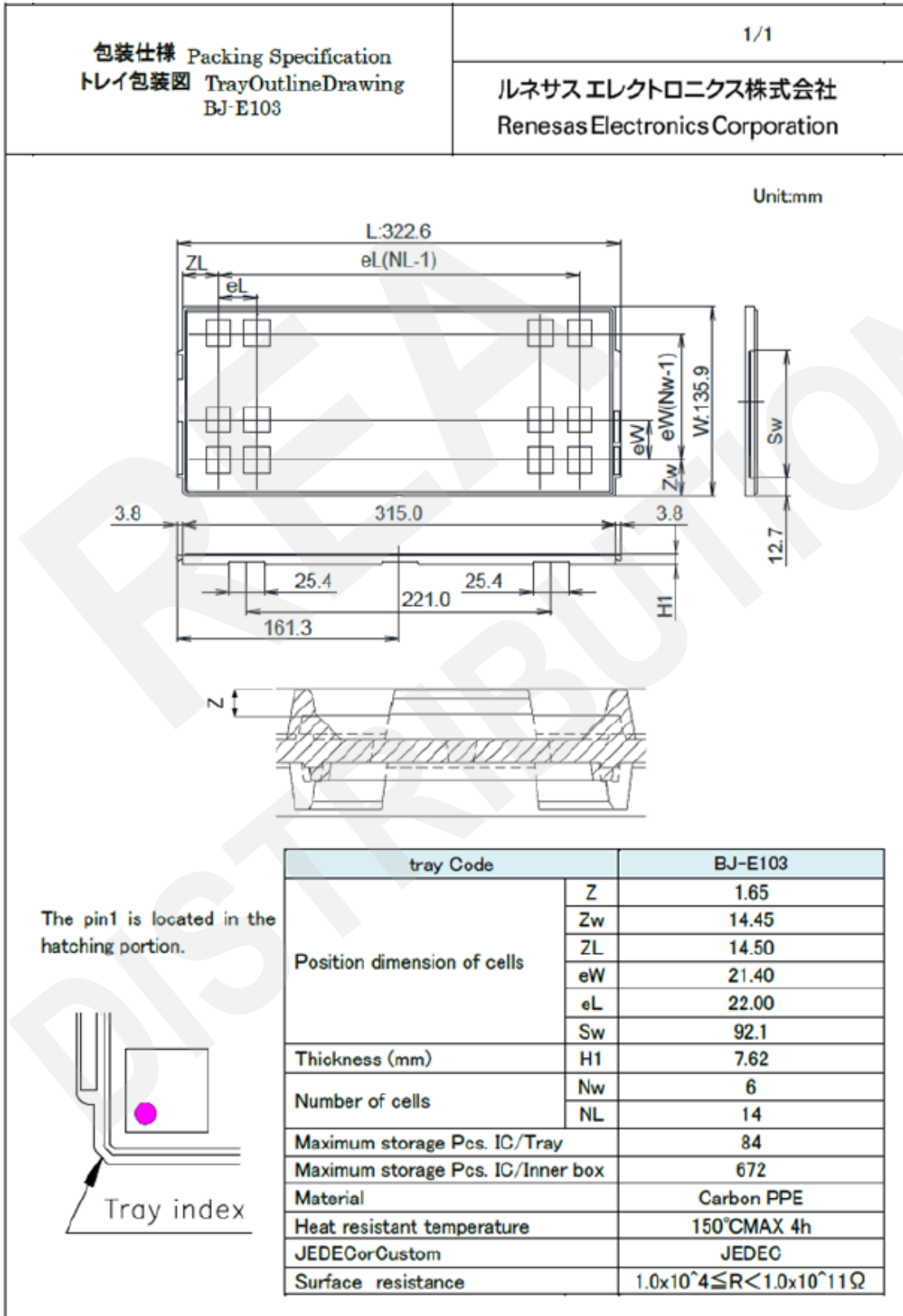
Appendix G: Package Outline Drawing for Additional Product

JEITA Package code	RENESAS code	MASS(TYP.)[g]
P-LFBGA320-17x17-0.80	PRBG0320GB-A	0.92



Reference Symbol	Dimension in Millimeters		
	Min.	Nom.	Max.
D1	—	17.00	—
E	—	17.00	—
D1	—	15.20	—
E1	—	15.20	—
A	—	—	1.75
A1	0.35	—	—
b	0.45	0.50	0.55
e	—	0.80	—
aaa	—	—	0.20
ccc	—	—	0.20
ddd	—	—	0.12
eee	—	—	0.20
fff	—	—	0.08
n	—	320	—

Appendix H: Packing Specification for Additional Product



## Appendix I: Reflow Soldering Conditions for Additional Product

実装条件 Mount Conditions リフローはんだ付け条件 Reflow Soldering Conditions	ルネサス エレクトロニクス株式会社 Renesas Electronics Corporation								
リフローはんだ付け方式 Reflow Soldering Method (IRリフロー炉、エアリフロー炉、エア+赤外線併用リフロー炉) (IR Reflow Air Reflow IR+Air Reflow)									
防湿包装開封後は再吸湿を避けるため、防湿包装開封後の保管条件以内に、 下記条件にてリフローはんだ付けを行ってください。 また、それ以上経過した場合はベーク条件で示すベーク処理を行ってください。 Please perform reflowing with following conditions within prescribed storage time after opening the moisture-proof packing in order not to make products be re- moisturized. If the time after opening the moisture-proof packing exceeds prescribed storage conditions, prescribed bake is necessary.									
1) 部品耐熱性 Heat Resistance									
<耐熱温度 Heat resistance temperature :260℃>									
<table border="1"> <tr> <td>最高リフロー温度 (パッケージ表面温度) Maximum temperature (Package surface temperature)</td> <td>260℃以下 Maximum 260℃</td> </tr> <tr> <td>255℃以上の時間 Over 255℃ Time</td> <td>30s 以下 ≤30 seconds</td> </tr> <tr> <td>217℃以上の時間 Time of temperature higher than 217℃</td> <td>60~150s 60 - 150 seconds</td> </tr> <tr> <td>プリヒート温度 150℃~200℃の時間 Preheating time at 150℃ to 200℃</td> <td>60~120s 60 - 120 seconds</td> </tr> </table>	最高リフロー温度 (パッケージ表面温度) Maximum temperature (Package surface temperature)	260℃以下 Maximum 260℃	255℃以上の時間 Over 255℃ Time	30s 以下 ≤30 seconds	217℃以上の時間 Time of temperature higher than 217℃	60~150s 60 - 150 seconds	プリヒート温度 150℃~200℃の時間 Preheating time at 150℃ to 200℃	60~120s 60 - 120 seconds	
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<p>パッケージ表面温度 Package Surface Temperature</p> <p>時間 time</p> <p>リフローはんだ付けプロファイル Reflow Soldering Profile</p>									
2) リフロー回数 : 3回以下 (防湿包装開封後の保管条件以内) Reflowing times: Maximum 3 times (Within prescribed time after opening moisture-proof packing.)									
3) リフロー雰囲気: エアもしくは窒素(N2) Reflowing atmosphere: Air or nitrogen atmosphere(N2)									